

REMARKS

The amendment to the claims 1 and 11 is supported by the original disclosure at page 6, line 8 and original claim 9. The amendment to claims 3, 4, 7 and 11 are supported by the original disclosure at page 6, lines 10-18, and page 7, structures I and II. Applicants submit that the amendments do not add any new matter to the disclosure.

Applicants hereby confirm the election of the invention of Group I, claims 1-11, 13 without traverse.

Applicants submit that the above amendments address the ambiguities in the original claims regarding the terms "cyclic ether" and "polycyclic moiety." On this basis, applicants submit that the claims are now in compliance with 35 USC 112, second paragraph.

The invention centers on novel planarizing underlayer compositions which are especially useful in combination with silicon-containing resists in lithographic processes using 193nm radiation to provide lithographic features free of unwanted artifacts. See example 2. These compositions are characterized by the presence of a polymer having a combination of epoxy, aromatic and fused polycyclic hydrocarbon moieties.

Hiwara et al. (US 6166100) discloses pigmented epoxy compositions containing a combination of epoxy, aromatic and cyclic hydrocarbon moieties. Applicants submit that Hiwara et al. does not disclose or suggest compositions containing fused polycyclic hydrocarbon moieties as required by the presently amended claims. Applicants further submit that it is not apparent that the compositions of Hiwara et al. would be suitable for use as planarizing

underlayers in lithographic processes.

Asakawa et al. (US 6280897) discloses resist compositions comprising various monomers. Applicants submit that Asakawa et al. does not disclose or suggest compositions containing epoxy moieties as required by the presently amended claims.

Perez et al. (US 6235850) discloses self-fixturing adhesive terpolymers. Perez et al. does not disclose or suggest fluorine-containing polymers, nor the use of the compositions as underlayers in lithographic structures.

For the above reasons, applicants submit that the claims are patentable over the prior art of record and that the application is in condition for allowance. Such allowance is earnestly and respectfully solicited.

Respectfully submitted,
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